



TARGET THICKNESS: 0.062"
NUMBER OF LAYERS: 08

MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

8 Layer StackUp (0.062") L08-062-2oz2oz		Thickness (inches)
Layer 1	2 oz foil plated to approximate* thickness 0.0038"	0.0038
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0064
Layer 2	2 oz foil thickness	0.0028
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 3	2 oz foil thickness	0.0028
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0064
Layer 4	2 oz foil thickness	0.0028
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 5	2 oz foil thickness	0.0028
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0064
Layer 6	2 oz foil thickness	0.0028
Core	Laminate Core Average Dielectric Constant 4.5	0.005
Layer 7	2 oz foil thickness	0.0028
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0064
Layer 8	2 oz foil plated to approximate* thickness 0.0038"	0.0038
"Thickness does not include soldermask or surface finish"		0.065

NOTES: